KDBSQB K G Q BSDQRSHBR

QL DSDQ	MCHSH MR	L A K	5 KTDR			MHS
			HM	O	W	
	℃					
	℃					
	℃					
	℃					
	℃					
	℃					
	℃					
	℃					

GDQL K G Q BSDQRSHBR

QL DSDQ	MCHSH MR	L A K	5 KTDR			MHS
			HM	O	W	

. QCDQMF (ME QL SHM

DUHBD	QJHMF	BJ FD	6 DHFGS	(MVDQ W	DQ CS M

CHB K KDBSQB K GDQL K G QBSDQRSHBR

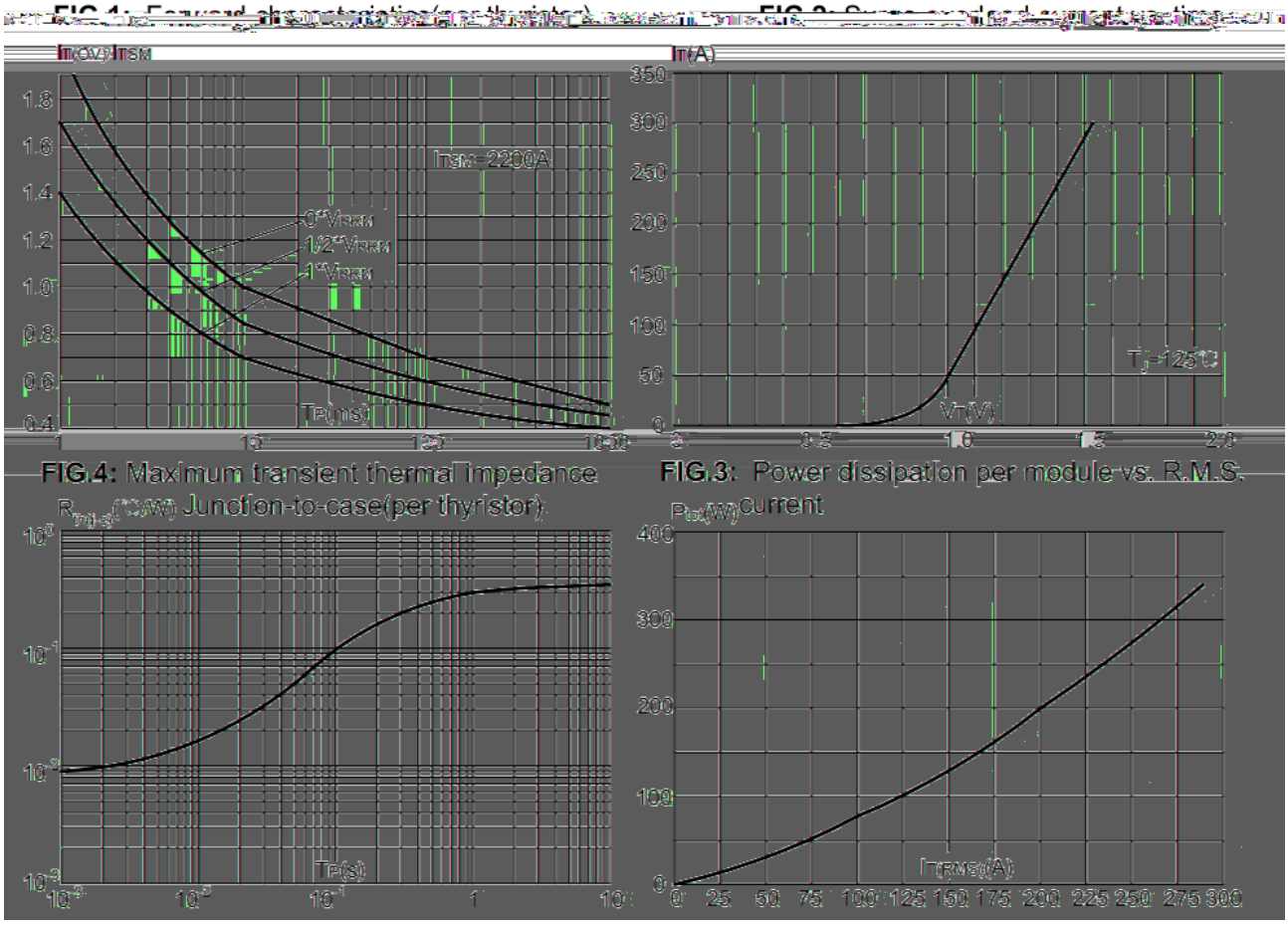
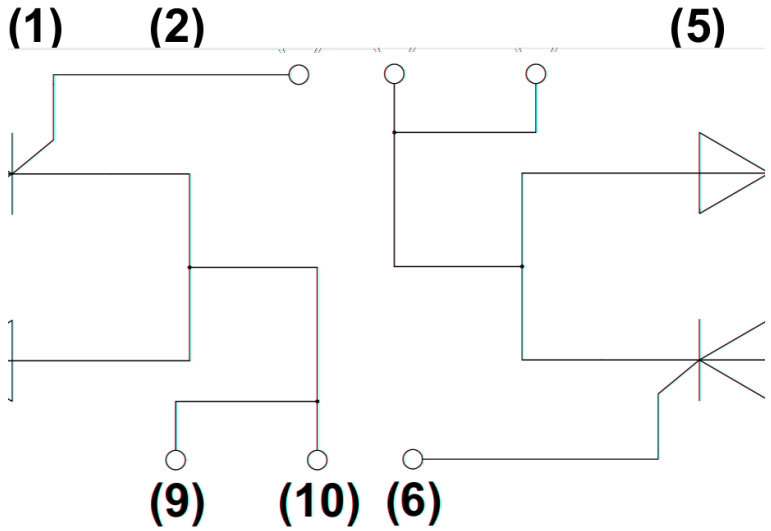


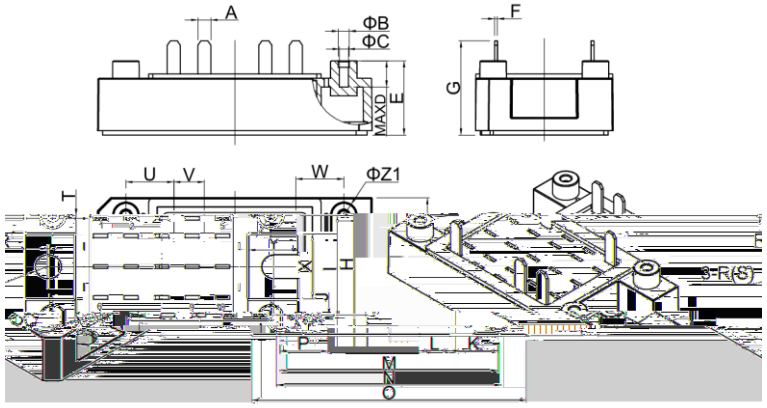
FIG.4: Maximum transient thermal impedance Junction-to-case(per thyristor)

FIG.3: Power dissipation per module vs. R.M.S. current

HQBTHS HFQL



BJ FD. TSKMDR L L



Ref	Dimensions				
	Millimeters			Inches	
	Min.	Nom.	Max.	Min.	Nom.
A	2.89	3	3.15	0.112	0.118
B	2.3	2.5	2.7	0.091	0.098
C	1.9	2.1	2.3	0.075	0.083
D			6		
E	16.25	17	17.75	0.640	0.669
F	0.55	0.65	0.75	0.022	0.026
G	20.85	21.6	22.35	0.821	0.850
L					
M	49.5	50	50.5	1.949	1.969
N	51	51.5	52	2.008	2.028
P					
W					